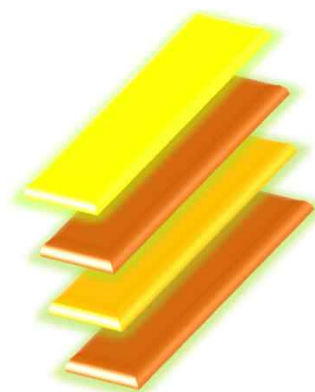


# Technical Data Sheet

1. Product Name: PI Gold Conductive Film (New sputtering method)

2. Product No: EPFC-028NG

3. Structure



**Au layer**

Cu layer  
Sputtered seed  
(Ni/Cu alloy)

**PI Film**



Item	Reference
Au + Cu	2~2.5μm
PI FILM	25μm
Total Thickness	28μm

\* Au 300A°

4. Characteristics

ITEM	STANDARD	REFERENCE
Material	Au + Cu + PI Film	
Thickness (μm)	28 ± 10%	
Width (mm)	250 ± 20	
Length (M/Roll)	50 - 100	
Color	Gold	
Surface resistivity (Ω/sq inch)	0.01-0.03	MIL-G-83528
Peel Strength (kg/cm)	Min 0.5	
RoHS	N.D.	

## Storage

-Avoid direct sunlight &, store indoor under the required temperature and humidity constantly.  
(Temperature : 22~28 °C , Humidity: 50±10 %RH)

## Precautions

-Forbid handling with bare hands for protecting surface and recommend to use clear gloves.  
-Be careful in handling it as excessive shock for prevent from surface damage.

## Guaranty Period

-For 3 months from the date of delivery without opening paper box and for 1 month with opening paper box providing the condition of storage and precaution requested as above.